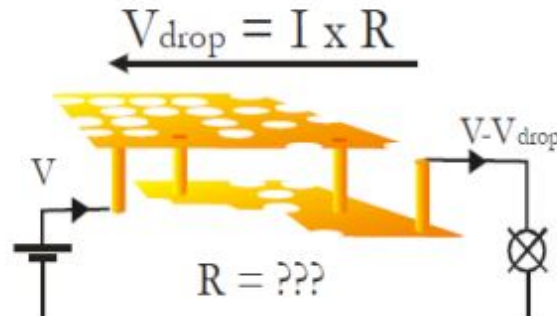


Physical Design Analysis

IR Drop Analysis

IR Drop



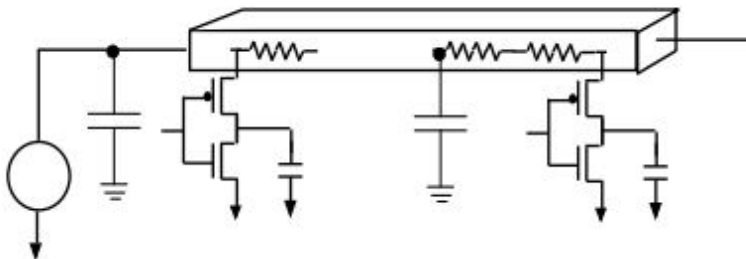
- The voltage that gets to the internal circuitry is less than that applied to the chip, since every metal layer offers resistance to the flow of current
- When a current, I passes through a conductor with resistor R , it exhibits a voltage drop V which is equal to the resistance times the current,

Ohm's law, $V=IR$

- IR Drop is defined as the average of the peak currents in the power network multiplied by the effective resistance from the power supply pads to the center of the chip
- IR Drop is a reduction in voltage that occurs on both Power and Ground networks
- IR Drop Analysis ensures that Power Delivery Network (PDN) is robust, and that your system will function to specification
- IR Drop is determined by the current flow and the supply voltage
- As distance between supply voltage and the component increases the IR Drop also increases

IR Drop Analysis

- IR Drop Analysis will compute the actual I_{DD} and I_{SS} currents, because these values are time-dependent
- IR Drop Analysis will compute Global IR drop which is important and more accurate, but cannot be compute separately (parallel) for smaller blocks, which may led to bigger run time



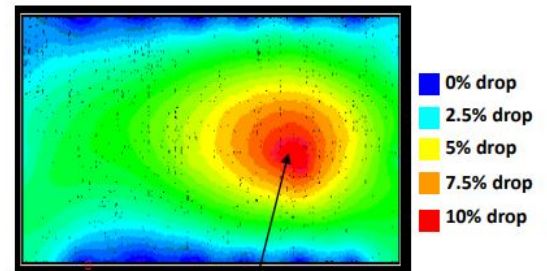
- **Local IR Drop**
 - IR Drop become a local phenomenon when a number of gates in close proximity switches at once
 - Local IR Drop can also be caused by a higher resistance to a specific portion of the Grid
- **Global IR Drop**
 - IR Drop is a global phenomenon when activity in one region of a chip causes an IR Drop in other regions
- In a well-meshed power grid with equally distributed currents, the power grid typically has a set of equipotential IR Drop surfaces that form concentric circles centered in the middle of the chip
- So the center of the chip usually has the largest IR Drop or the lowest supply voltage

- Peak IR Drop is much larger than the Average IR Drop
- Peak IR Drop happens in the worst-case switch patterns of the gates

Types of IR Drop

Static IR Drop

- Static IR drop is average voltage drop for the design
- The average current depends totally on the time period
- Static IR drop was good for signoff analysis in older technology nodes where sufficient natural decoupling capacitance from the power network and non-switching logic were available
- Localized switching is only considered
- Only be a few % of the supply voltage
- Can be reduced by lowering the resistance of Supply and Signal Paths



•Typical static voltage drop bulls-eye of an appropriately constructed power grid
 •But 10% static voltage drop is very high

Static IR Drop methodology

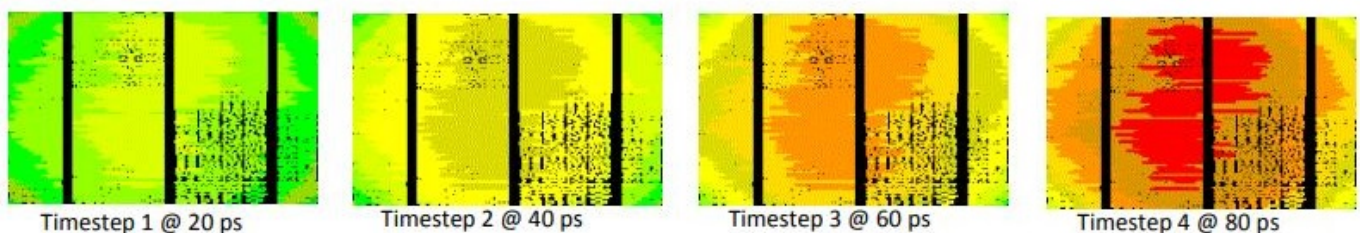
- Extract power grid to obtain R
- Select stimulus
- Compute time averaged power consumption for a typical operation to obtain I(current)
- Compute: $V = IR$
- Non time-varying

Dynamic IR Drop

- When large amounts of circuitry switch simultaneously causing peak current demand
- Dynamic IR drop is mainly due to Instantaneous Voltage Drop (IVD) and it can be controlled by inserting Decap Cells in the Power network
- Dynamic IR drop depends on switching activity and switching time of the logic and is less dependent on the a clock period
- Instantaneous current demand could be highly localized and could be brief within a single clock cycle (a few hundred ps)
- Vector dependent, so VCD-based analysis is required

Dynamic IR Drop methodology

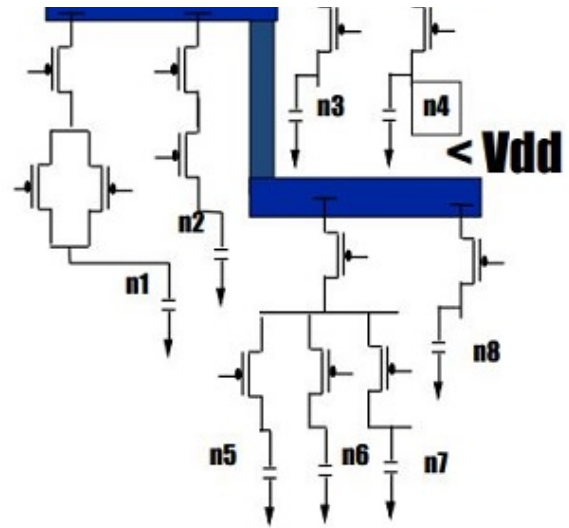
- Extract power grid to obtain on-chip R and C
- Include RLC model of the package and bond wires
- Select stimulus
- Compute time varying power for specific operation to obtain I(t)
- Compute $V(t) = I(t) \cdot R + C \cdot dv/dt \cdot R + L \cdot di/dt$



IR Drop: Reasons



- Improper placement of Power/Ground Pads
- Wrong Block placement
- Bad global power routing
- Insufficient Core Ring, Power Strap width
- Lesser no of Power Straps
- Missing Vias
- Insufficient number of Power Pads

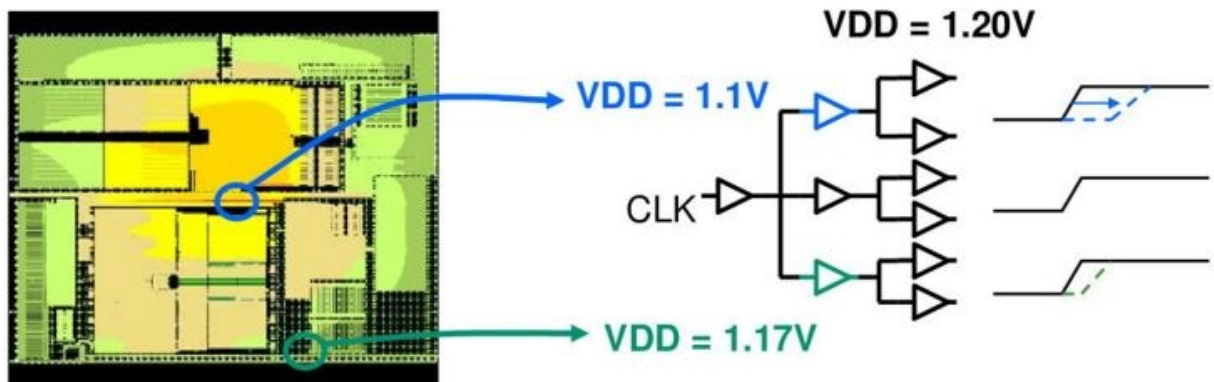


IR Drop: Robustness Checks

- Open circuits
- Missing or insufficient Vias
- Current Density violations
- Insufficient Power Rail design

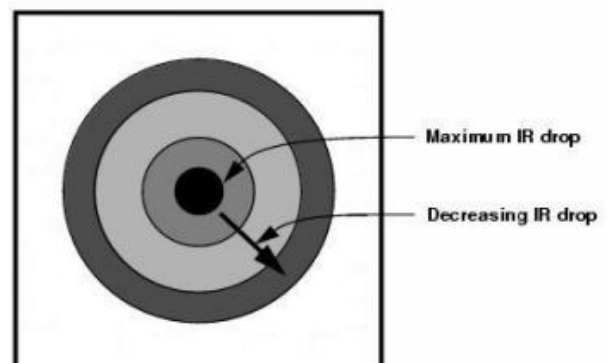
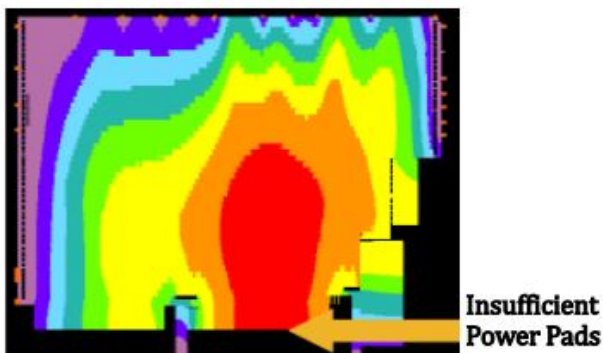
IR Drop: Impacts

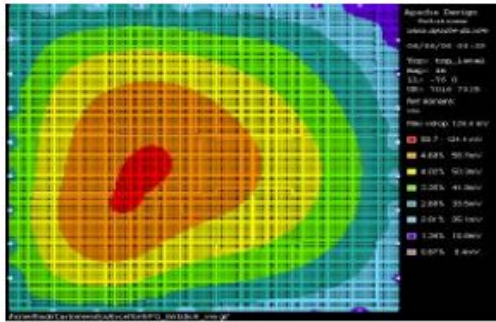
- IR Drop Analysis confirms that the worst case voltage drop (which is considered for the worst corner for timing) on a chip meets IR Drop targets
- Impacts in Timing
 - If this Voltage Drop is too severe, the circuit will not get enough voltage, resulting in the malfunction or timing failure
 - If IR Drop increases Clock Skew then it will result in Hold Time Violations
 - If IR Drop increases Signal Skew then it will result in Setup Time Violations



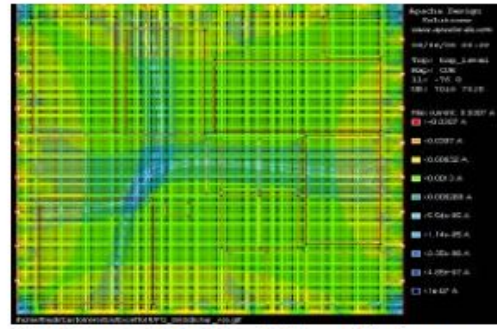
IR Drop Plot

Power grid has a set of equipotential surfaces that form concentric circles centered in the middle of a block





IR Drop Plot – Before fixing



IR Drop Plot – After fixing

IR Drop: Remedies

- Stagger the firing of buffers (bad idea: increases skew)
- Use different power grid tap points for clock buffers (but it makes routing more complicated for automated tools)
- Use smaller buffers (but it degrades edge rates/increases delay)
- Rearrange blocks
- More VDD pins
- Connect bottom portion of grid to top portion
- Distributing supplies symmetrically on the chip
- Lowering the resistance of Supply and Signal Paths by making supply wires thicker in dimensions than signal wires, $R = \rho \cdot L / A$
- Decap insertion can solve Dynamic IR drop, at later stage of the design
- Amount of decap depends on:
 - Acceptable ripple on VDD-VSS (typically 10% noise budget)
 - Switching activity of logic circuits (usually need 10X switched cap)
 - Current provided by power grid (di/dt)
 - Required frequency response (high frequency operation)

Ldi/dt Effects

- In addition to IR drop, power system inductance is also an issue
- Inductance may be due to power pin, power bump or power grid
- Overall voltage drop is:

$$V_{drop} = IR + L di/dt$$

- As a solution to this effect, distribute decoupling capacitors (decaps) liberally throughout design

